spirit or scope of the invention as defined in the appended claims.

What is claimed is:

1. A data processing card system, comprising:

(a) means for mounting at least one circuit chip device, said circuit chip mounting means including first flexible carrier means comprising an electrically insulating tape layer member having at least one aperture formed therethrough for registry with predetermined electrically active areas of said chip device and a plurality of electrically conductive lead members secured to said insulating tape member and extending within said aperture for coupling to said active areas of said chip device;

(b) substrate carrier means formed of a substantially rigid, electrically insulated and thermally conductive member composition located adjacent said circuit chip device mounting means, said substrate carrier means having at least a first predetermined electrical lead pattern formed thereon, said first electrical lead pattern being electrically coupled to predetermined contact areas of said circuit chip device; and,

(c) means for substantially isolating said combined substrate carrier means and said circuit chip device mounting means from an external environment.

2. The data processing card system as recited in claim 1 including a plurality of circuit chip devices coupled to said circuit chip device mounting means.

3. The data processing card system as recited in claim 2 where a predetermined set of circuit chip devices are electrically coupled to said first electrical lead patterm formed on said substrate carrier means.

4. The data processing card system as recited in claim 2 where at least one of said circuit chip devices is a chip memory device.

5. The data processing card system as recited in claim 4 where at least one of said chip memory devices is an electrically erasable programmable read only memory device.

6. The data processing card system as recited in claim 1 where at least one of said electrically conductive lead members is coupled to said circuit chip device on an upper surface and is coupled to said first electrical lead pattern on a lower surface.

7. The data processing card system as recited in claim 1 where said electrically conductive lead members are formed of an electrically conductive foil layer.

8. The data processing card system as recited in claim 1 where said circuit chip memory is an electrically erasable programmable read only memory device.

9. The data processing card system as recited in claim 1 where said circuit chip device mounting means includes a dimensional thickness within the approximating range of 0.005 to 0.01 inches.

10. The data processing card system as recited in claim 1 where said circuit chip device includes a dimensional thickness within the approximating range of 0.01 to 0.04 inches.

11. The data processing card system as recited in claim 1 where said substrate carrier means is formed of a substantially electrically insulative material composition.

12. The data processing card system as recited in claim 11 where said substrate carrier means is formed of a substantially thermally conductive material composition.

13. The data processing card system as recited in claim 13 where said substrate carrier means includes a substantially planar substrate member having an upper surface and a lower surface.

14. The data processing card system as recited in claim 13 where said substantially planar substrate member upper surface has said first predetermined electrical lead pattern formed thereon.

15. The data processing card system as recited in claim 14 where said first predetermined electrical lead pattern is photo-etched into said upper surface of said substantially planar substrate member.

16. The data processing card system as recited in claim 14 including means for electrically coupling at least a pair of circuit chip devices each to the other between predetermined contact areas, said chip electrical coupling means being sandwiched between said substrate carrier means and said circuit chip mounting means.

17. The data processing card system as recited in claim 16 where said chip electrical coupling means includes first chip coupling flexible carrier means for electrically coupling said predetermined chip contact areas each to the other.

18. The data processing card system as recited in claim 17 where said first chip coupling flexible carrier means includes:

(a) an electrically insulating tape member having opposed first and second surfaces; and,

(b) a plurality of electrically conductive chip coupling lead members secured to said first surface of said electrically insulating tape member, said second surface of said electrically insulating tape member being positionally located adjacent said upper surface of said substantially planar substrate member.

19. The data processing card system as recited in claim 18 where said electrically conductive chip coupling lead members are formed of an electrically conductive foil layer.

20. The data processing card system as recited in claim 15 where said first predetermined electrical lead pattern includes at least one electrical coupling line extending to a peripheral boundary of said substantially planar substrate member for electrically connecting said data processing system to an external electrical device.

21. The data processing card system as recited in claim 14 including at least a second predetermined electrical lead pattern formed on said lower surface of said substantially planar substrate member.

22. The data processing card system as recited in claim 21 where said means for mounting said circuit chip device includes second flexible carrier means having at least a second circuit chip device mounted thereto, said second circuit chip device being electrically coupled to said second predetermined lead pattern.

23. The data processing card system as recited in claim 22 including means for electrically coupling at least a pair of second circuit chip devices each to the other between predetermined contact areas, said means for electrically coupling said second circuit chip devices being sandwiched between said substrate carrier means and said second flexible carrier means.

24. The data processing card system as recited in claim 23 where said second chip coupling means includes second chip coupling flexible carrier means for